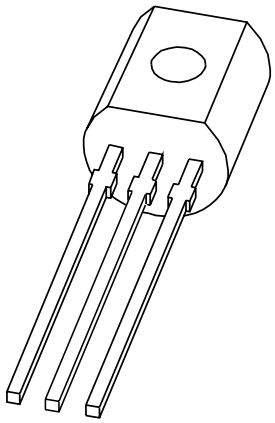
DATA SHEET



BF420; BF422
NPN high-voltage transistors

Product data sheet
Supersedes data of 1996 Dec 09

2004 Nov 10

NPN high-voltage transistors BF420; BF422

FEATURES

- Low feedback capacitance.

APPLICATIONS

- Class-B video output stages in colour television and professional monitor equipment.

DESCRIPTION

NPN transistors in a TO-92 plastic package.
PNP complements: BF421 and BF423.

PINNING

PIN	DESCRIPTION
1	base
2	collector
3	emitter

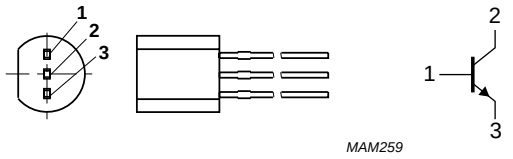


Fig.1 Simplified outline (TO-92) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF420	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BF422			

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BF420		–	300	V
	BF422		–	250	V
V_{CEO}	collector-emitter voltage	open base			
	BF420		–	300	V
	BF422		–	250	V
I_{CM}	peak collector current		–	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	–	830	mW
h_{FE}	DC current gain	V_{CE} = 20 V; I_C = 25 mA	50	–	
C_{re}	feedback capacitance	V_{CE} = 30 V; I_C = i_c = 0 A; f = 1 MHz	–	1.6	pF
f_T	transition frequency	V_{CE} = 10 V; I_C = 10 mA; f = 100 MHz	60	–	MHz

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BF420		–	300	V
	BF422		–	250	V
V_{CEO}	collector-emitter voltage	open base			
	BF420		–	300	V
	BF422		–	250	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	50	mA
I_{CM}	peak collector current		–	100	mA
I_{BM}	peak base current		–	50	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	830	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	ambient temperature		–65	+150	°C

Note

1. Transistor mounted on a printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	150	K/W

Note

1. Transistor mounted on a printed-circuit board.

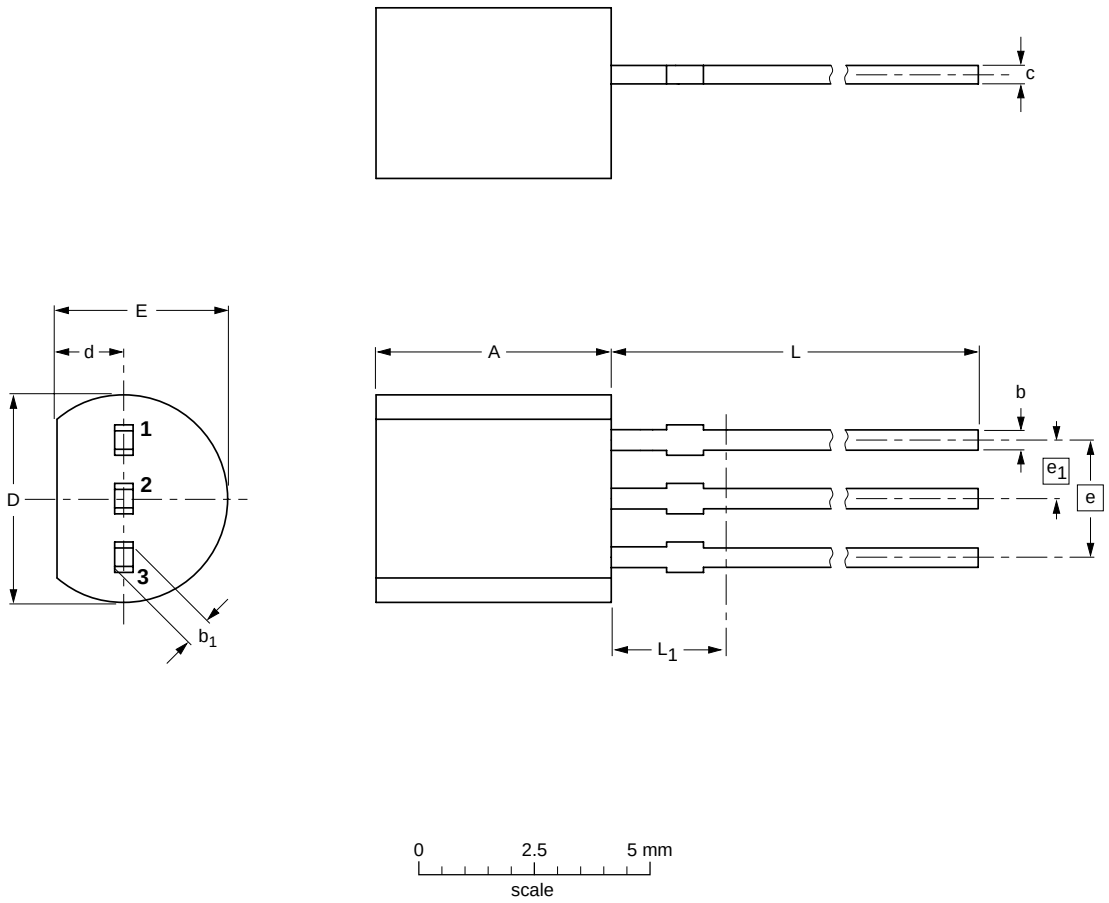
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	V_{CB} = 200 V; I_E = 0 A	–	10	nA
		V_{CB} = 200 V; I_E = 0 A; T_j = 150 °C	–	10	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A	–	50	nA
h_{FE}	DC current gain	V_{CE} = 20 V; I_C = 25 mA	50	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = 30 mA; I_B = 5 mA	–	0.6	V
C_{re}	feedback capacitance	V_{CE} = 30 V; $I_C = i_c$ = 0 A; f = 1 MHz	–	1.6	pF
f_T	transition frequency	V_{CE} = 10 V; I_C = 10 mA; f = 100 MHz	60	–	MHz

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	L_1 (1) max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~04-06-28~~ 04-11-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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